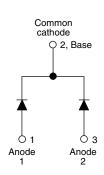
# VS-HFA16PA60C-N3

Vishay Semiconductors

## HEXFRED<sup>®</sup> Ultrafast Soft Recovery Diode, 2 x 8 A



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PRIMARY CHARACTERISTICS								
I <sub>F(AV)</sub>	2 x 8 A							
V <sub>R</sub>	600 V							
V <sub>F</sub> at I <sub>F</sub>	1.4 V							
t <sub>rr</sub> typ.	18 ns							
T <sub>J</sub> max.	150 °C							
Package	TO-247AC 3L							
Circuit configuration	Common cathode							

### FEATURES

- Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

### DESCRIPTION

VS-HFA16PA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16PA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I<sub>RRM</sub>) and does not exhibit any tendency to "snap-off" during the t<sub>b</sub> portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16PA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS					
Cathode to anode voltage	V <sub>R</sub>		600	V					
Maximum continuous forward currentper leg	I	T <sub>C</sub> = 100 °C	8						
per device	l <sub>F</sub>	$1_{\rm C} = 100$ C	16	А					
Single pulse forward current	I <sub>FSM</sub>	t <sub>p</sub> = 10 ms	60	A					
Maximum repetitive forward current	I <sub>FRM</sub>		24						
Maximum power dissipation	PD	T <sub>C</sub> = 25 °C	36	W					
	ΓD	T <sub>C</sub> = 100 °C	14	vV					
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C					

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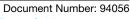
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<b>ELECTRICAL SPECIFICATIONS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V <sub>BR</sub>	I <sub>R</sub> = 100 μA	600	-	-			
Maximum forward voltage		I <sub>F</sub> = 8.0 A		-	1.4	1.7	v	
	V <sub>FM</sub>	I <sub>F</sub> = 16 A	See fig. 1	-	1.7	2.1		
		$I_F = 8.0 \text{ A}, T_J = 125 \text{ °C}$		-	1.4	1.7		
Maximum reverse		$V_R = V_R$ rated	Coofig 0	-	0.3	5.0		
leakage current		$T_J$ = 125 °C, $V_R$ = 0.8 x $V_R$ rated	See fig. 2	-	100	500	μA	
Junction capacitance	CT	V <sub>R</sub> = 200 V See fig. 3		-	10	25	pF	
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from p	ackage body	-	8.0	-	nH	

<b>DYNAMIC RECOVERY CHARACTERISTICS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS MIN. TYP. MAX.						
Reverse recovery time See fig. 5, 6 and 16	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, \text{ d}I_F/\text{d}t = 200$	I <sub>F</sub> = 1.0 A, dI <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 30 V		18	-			
	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	37	55	ns		
	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C	I <sub>F</sub> = 8.0 A dI <sub>F</sub> /dt = 200 A/μs V <sub>R</sub> = 200 V	-	55	90			
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	3.5	5.0	A nC		
See fig. 7 and 8	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C		-	4.5	8.0			
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	65	138			
See fig. 9 and 10	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	124	360	ne		
Peak rate of fall recovery current during $t_b$ See fig. 11 and 12	dl <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	240	-	A∕µs		
	dl <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	210	-	-ν μο		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C		
Junction to case, single leg conducting			-	-	3.5			
Junction to case, both leg conducting	R <sub>thJC</sub>		-	-	1.75	K/W		
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	40	r./ vv		
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth, and greased	-	0.25	-			
Weight			-	6.0	-	g		
weight			-	0.21	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-247AC 3L		HFA16PA60C				

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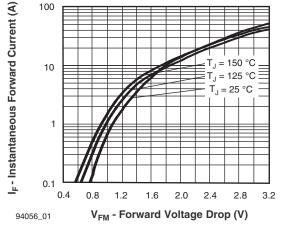


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

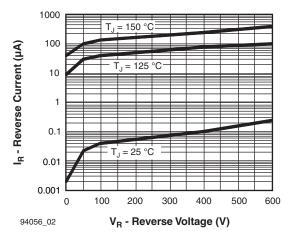


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

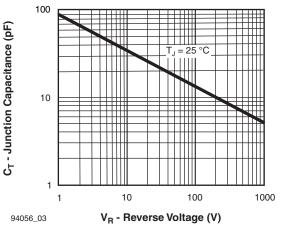
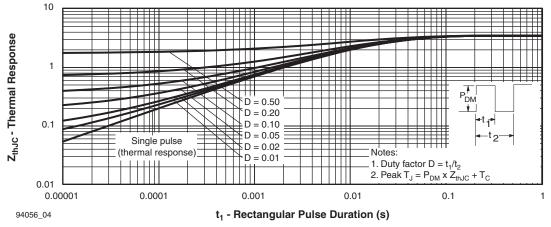


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)





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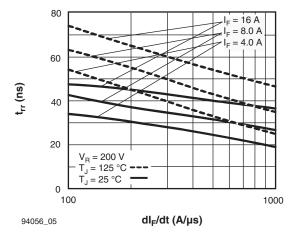


Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt (Per Leg)

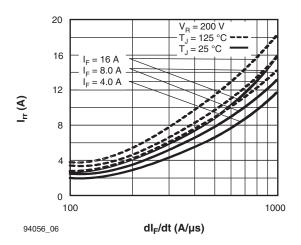


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)

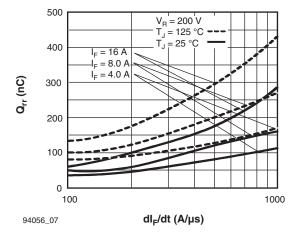


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

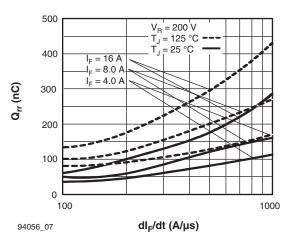


Fig. 8 - Typical dI<sub>(rec)M</sub>/dt vs. dI<sub>F</sub>/dt (Per Leg)

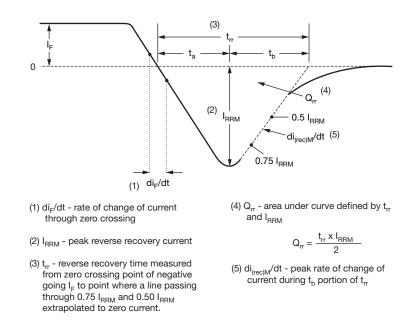


Fig. 9 - Reverse Recovery Waveform and Definitions

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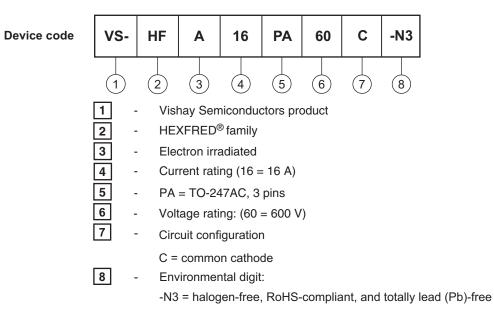
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#### **ORDERING INFORMATION TABLE**



ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-HFA16PA60C-N3	25	500	Antistatic plastic tube						

LINKS TO RELATED DOCUMENTS					
Dimensions www.vishay.com/doc?96138					
Part marking information	www.vishay.com/doc?95007				
SPICE model	www.vishay.com/doc?96596				



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TO-247AC 3L

#### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INC	HES	NOTES	SYMBOL		IETERS	INC	HES	NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	STWDOL	MIN.	MAX.	MIN.	MAX.	NOTES
A	4.65	5.31	0.183	0.209		D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102		E	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054		E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055		е	5.46	BSC	0.215	5 BSC	
b1	0.99	1.35	0.039	0.053		ØК	0.2	254	0.0	)10	
b2	1.65	2.39	0.065	0.094		L	14.20	16.10	0.559	0.634	
b3	1.65	2.34	0.065	0.092		L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135		ØΡ	3.56	3.66	0.14	0.144	
b5	2.59	3.38	0.102	0.133		Ø P1	-	7.39	-	0.291	
С	0.38	0.89	0.015	0.035		Q	5.31	5.69	0.209	0.224	
c1	0.38	0.84	0.015	0.033		R	4.52	5.49	0.178	0.216	
D	19.71	20.70	0.776	0.815	3	S	5.51	BSC	0.217	' BSC	
D1	13.08	-	0.515	-	4						

#### Notes

<sup>(1)</sup> Dimensioning and tolerancing per ASME Y14.5M-1994

(2) Contour of slot optional

(3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body

(4) Thermal pad contour optional with dimensions D1 and E1

<sup>(5)</sup> Lead finish uncontrolled in L1

<sup>(6)</sup> Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")

<sup>(7)</sup> Outline conforms to JEDEC<sup>®</sup> outline TO-247 with exception of dimension Q

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